ADVANCED PACKAGING

Large-area panel bonding for panel sizes up to 510 × 510 mm, extendable up to 610 × 610 mm

INFOTECH automation

INFOTECH
ADVANCED PACKAGING

Advanced Packaging enables next-generation semiconductor assemblies with higher precision, greater integration, and improved electrical / thermal performance compared to conventional packaging.

Supports high accuracy die bonding, flip chip bonding and advanced joining processes including inert gas environments, scalable from lead frame and substrate to wafer (including FOUP support) and panel-level processes. Secondary processes are supported with all dispensing applications, AI vision inspection, testing, or underfill, supporting complete Production Lines.

- Large-area panel bonding up to 610 × 610 mm
- Scalable platform for next-generation packaging and higher throughput
- Increase UPH through parallel material feeding and processing
- FOUP Magazine support

Parallelization

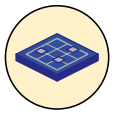
IB-Wafer Feeder with adjustable transport system

Parallel processing instead of sequential with extended conveyor range to a depth of up to 610 mm.

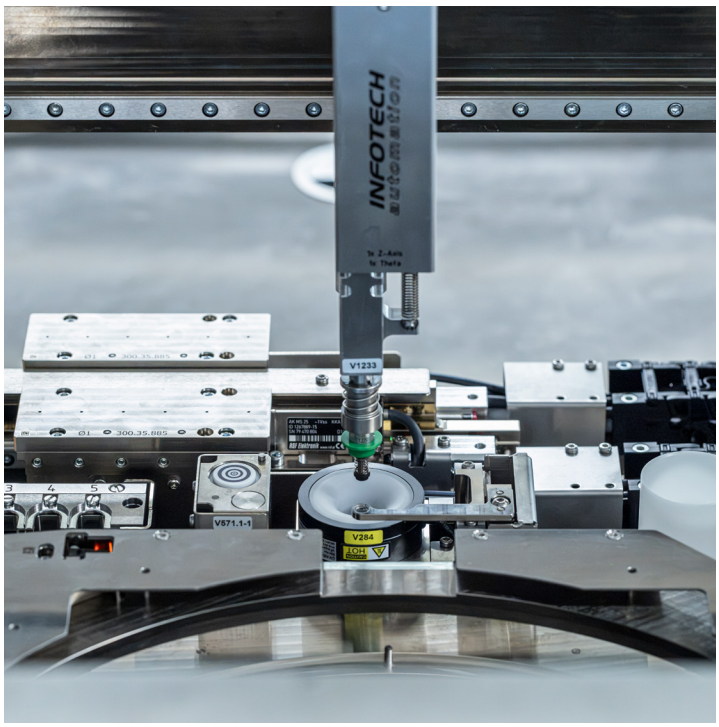
The Infotech IB-Wafer Feeder delivers reliable, automated handling and continuous die supply to keep your bonding process running efficiently.

Supporting large panels, it combines stable loading / unloading of dies with precise positioning for high-throughput, repeatable production while reducing operator effort and downtime.

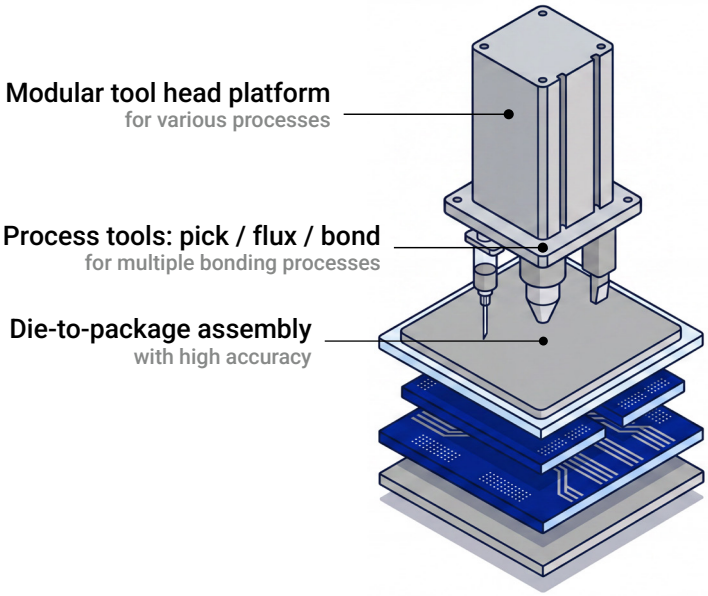
Panel-Size
HANDLING & TRAVEL RANGE



Parallel
FEEDING & PROCESSING



Die Assembly

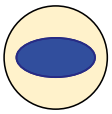


Advanced Packaging Automation

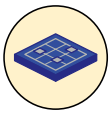
From die to package with automated assembly.

Dispensing · Flip-chip die attach · Sinter bonding · Diffusion bonding · Lid attach · Ultrasonic welding · Pin attach · KGD testing · Large-die handling

C2W
CHIP-TO-WAFER



CoP
CHIP-ON-PANEL



C2S
CHIP-TO-SUBSTRATE

Large Die
HANDLING

www.infotech-automation.com
info@infotech.swiss
Tel. +41 32 626 86 00

Technologiestrasse 1
2540 Grenchen
Switzerland

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